

PATENT APPLICATION TRANSMITTAL LETTER

(Large Entity)

Docket No. 50623.149

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F. R. 1.53 is the patent application of: Stephen D. Pacetti; Wouter E. Roorda; Ni Ding



| For: | A System An | d Method For Co | oating Implantabl | e Devices | | | | j 10 | | |
|--------|--|---|--|---|-----------------------------|-----------|--------------|------------|--|--|
| | ✓ 15 sheets of Informal Drawings ✓ Assignment including Form PTO-1595. ✓ Declaration ☐ Signed ☑ Unsigned. ✓ Power of Attorney ✓ Information Disclosure Statement ✓ Preliminary Amendment | | | | | | | | | |
| L. | | | | | | | | | | |
| | For | #Filed | #Allowed | #Extra | | Rate | | Fee | | |
| *** | al Claims | 32 | - 20 = | 12 | х | \$18.00 | | \$216.00 | | |
| Inde | p. Claims | 3 | - 3≃ | 0 | х | \$80.00 | | \$80.00 | | |
| Mul | Multiple Dependent Claims (check if applicable) \$0.00 | | | | | | | \$0.00 | | |
| | | | | | | | BASIC FEE | \$740.00 | | |
| i | | | | | | TOTA | L FILING FEE | \$1,036.00 | | |
| ⊠ ⊠ | The Commission as described by Charge the Credit and Charge at Charge the Cha | oner is herby au elow. A duplica ne amount of \$_ y overpayment. ny additional filir ne issue fee set it to 37 C.F.R. 1.3 | 36.00 to cover the athorized to charge te copy of this shear as filing fees required to the shear and the shear as filling fees required to the shear and the shear as filling fees required to the shear and the shear and the shear as filling fees required to the shear and the shear as filling fees required to the shear and the shear and the shear as filling fees and the shear an | e and credit D eet is enclose ng fee. under 37 C.F.F | eposit A d. R. 1.16 a | ind 1.17. | | | | |

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number

| First Named Inventor Stephen D. Pacetti | |
|---|--|
| OCERTIFICATION UNDER A System And Method For Coating S.C. 122(b)(2)(B)(i) Pitle Implantable Devices | |
| Atty Docket Number 50623 149 | |

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multinational agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).



Paul J. Meyer, Jr., Esq.

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application upon filing.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Washington, DC 20231